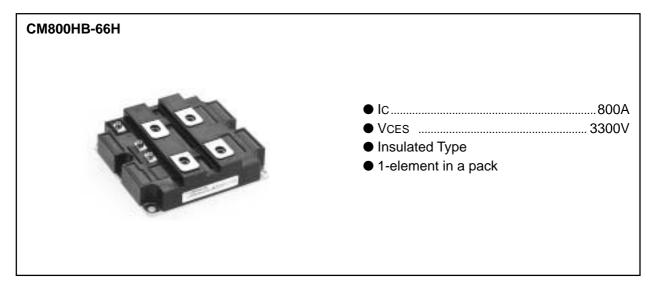
MITSUBISHI HVIGBT MODULES

CM800HB-66H

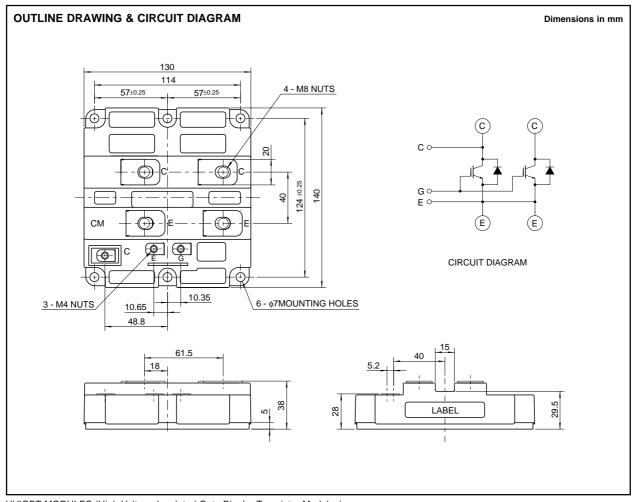
HIGH POWER SWITCHING USE
INSULATED TYPE

2nd-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



APPLICATION

Inverters, Converters, DC choppers, Induction heating, DC to DC converters.



HVIGBT MODULES (High Voltage Insulated Gate Bipolar Transistor Modules)



CM800HB-66H

HIGH POWER SWITCHING USE INSULATED TYPE

2nd-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

MAXIMUM RATINGS (Tj = 25°C)

Symbol	Item	Conditions	Ratings	Unit	
VCES	Collector-emitter voltage	VGE = 0V	3300	V	
VGES	Gate-emitter voltage	VCE = 0V	±20	V	
Ic	Collector current	DC, Tc = 100°C	800	Α	
Ісм	Collector current	Pulse	1600	Α	
IE (Note 2)	Emitter current		800	Α	
IEM(Note 2)	Emilier current	Pulse	(Note 1)	1600	Α
PC (Note 3)	Maximum collector dissipation	Tc = 25°C, IGBT part		10400	W
Tj	Junction temperature	_	-40 ~ + 150	°C	
Tstg	Storage temperature	_	− 40 ~ + 125	°C	
Viso	Isolation voltage	Charged part to base plate, rms, sinusoi	6000	V	
_	Mounting torque	Main terminals screw M8	6.67 ~ 13.00	N⋅m	
		Mounting screw M6	2.84 ~ 6.00	N⋅m	
		Auxiliary terminals screw M4	0.88 ~ 2.00	N⋅m	
_	Mass	Typical value	1.5	kg	

ELECTRICAL CHARACTERISTICS (Tj = 25°C)

Symbol	Itom	Conditions		Limits			Unit	
	Item			Min	Тур	Max	Unit	
ICES	Collector cutoff current	VCE = VCES, VGE = 0V			_	_	10	mA
VGE(th)	Gate-emitter threshold voltage	IC = 80mA, VCE = 10V			4.5	6.0	7.5	٧
IGES	Gate-leakage current	VGE = VGES, VCE = 0V			_	_	0.5	μΑ
VCE(sat)	Collector-emitter	Tj = 25°C	In 0004 \/o= 45\/	(1)	_	3.80	4.94	V
	saturation voltage	Tj = 125°C	IC = 800A, VGE = 15V	(Note 4)	_	4.00	_	
Cies	Input capacitance	VCE = 10V		_	120	_	nF	
Coes	Output capacitance	VGE = 10V			_	12.0	_	nF
Cres	Reverse transfer capacitance				_	3.6	_	nF
QG	Total gate charge	VCC = 1650V, IC = 800A, VGE = 15V			_	5.7	_	μС
td (on)	Turn-on delay time	Vcc = 1650V, Ic = 800A		_	_	1.60	μs	
tr	Turn-on rise time	VGE1 = VGE2 = 15V			_	_	2.00	μs
td (off)	Turn-off delay time	$RG = 2.5\Omega$			_	_	2.50	μs
tf	Turn-off fall time	Resistive load switching operation			_	_	1.00	μs
VEC(Note 2)	Emitter-collector voltage	IE = 800A, VGE = 0V			_	2.80	3.64	V
trr (Note 2)	Reverse recovery time	IE = 800A,			_	_	1.40	μs
Qrr (Note 2)	Reverse recovery charge	die / dt = -1600	0A / μs	(Note 1)	_	270	_	μC
Rth(j-c)Q	Th	Junction to case, IGBT part		_	_	0.012	K/W	
Rth(j-c)R	Thermal resistance	Junction to case, FWDi part		_	_	0.024	K/W	
Rth(c-f)	Contact thermal resistance	Case to fin, conductive grease applied			_	0.008	_	K/W

Note 1. Pulse width and repetition rate should be such that the device junction temp. (Tj) does not exceed T_{jmax} rating.

2. IE, VEC, trr, Qrr & die/dt represent characteristics of the anti-parallel, emitter to collector free-wheel diode.

3. Junction temperature (Tj) should not increase beyond 150°C.

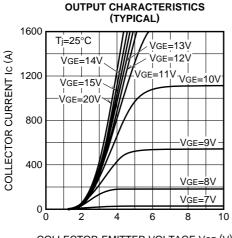


^{4.} Pulse width and repetition rate should be such as to cause negligible temperature rise.

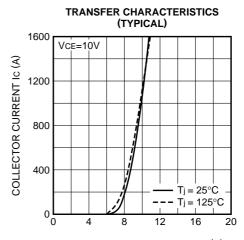
CM800HB-66H

HIGH POWER SWITCHING USE INSULATED TYPE

PERFORMANCE CURVES

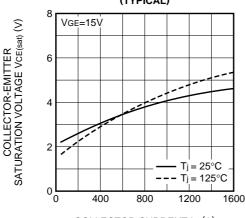


COLLECTOR-EMITTER VOLTAGE VCE (V)



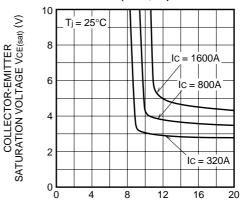
GATE-EMITTER VOLTAGE VGE (V)

COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



COLLECTOR CURRENT IC (A)

COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)

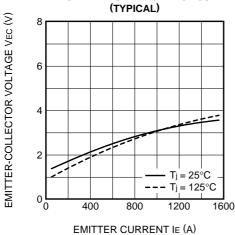


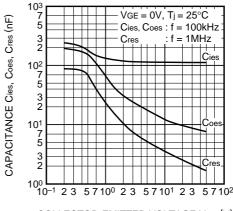
GATE-EMITTER VOLTAGE VGE (V)

CAPACITANCE CHARACTERISTICS

(TYPICAL)

FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)





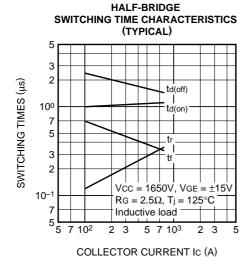
COLLECTOR-EMITTER VOLTAGE VCE (V)



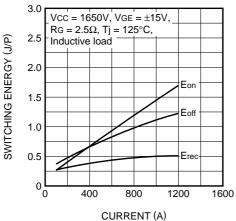
CM800HB-66H

HIGH POWER SWITCHING USE INSULATED TYPE

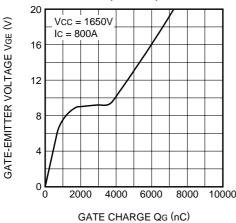
2nd-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



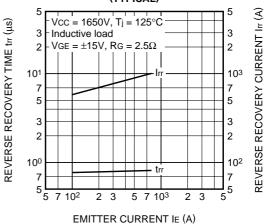
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



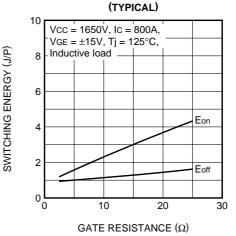
GATE CHARGE CHARACTERISTICS (TYPICAL)



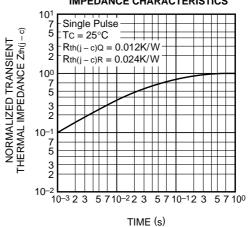
REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



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